



## STC5NF20V

N-channel 20V - 0.030Ω - 5A - TSSOP8  
2.7V-drive STripFET™ II Power MOSFET

### General features

Type	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
STC5NF20V	20V	< 0.040 Ω (@ 4.5 V) < 0.045 Ω (@ 2.7 V)	5A

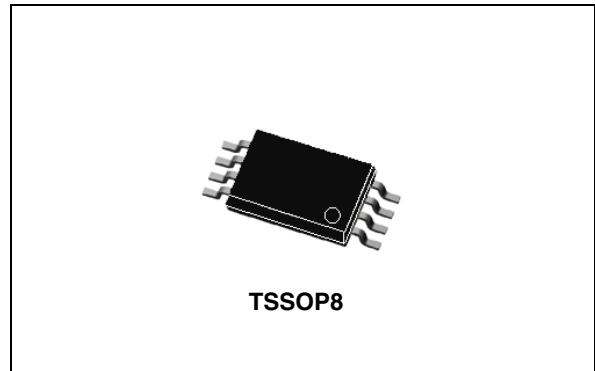
- Ultra low threshold gate drive (2.7V)
- Standard outline for easy automated surface mount assembly

### Description

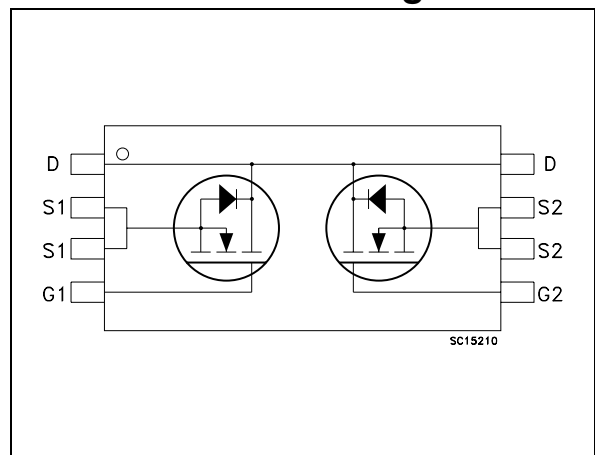
This Power MOSFET is the latest development of STMicroelectronics unique "Single Feature Size™" strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

### Applications

- Switching application



### Internal schematic diagram



### Order codes

Part number	Marking	Package	Packaging
STC5NF20V	C5NF20V	TSSOP8	Tape & reel

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# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage ( $V_{GS} = 0$ )	20	V
$V_{DGR}$	Drain-gate voltage ( $R_{GS} = 20K\Omega$ )	20	V
$V_{GS}$	Gate-source voltage	$\pm 12$	V
$I_D$	Drain current (continuous) at $T_C = 25^\circ C$	5	A
$I_D$	Drain current (continuous) at $T_C = 100^\circ C$	3	A
$I_{DM}^{(1)}$	Drain current (pulsed)	20	A
$P_{TOT}$	Total dissipation at $T_C = 25^\circ C$	1.5	W
$T_{stg}$	Storage temperature	-55 to 150	$^\circ C$
$T_J$	Max. Operating junction temperature	-55 to 150	$^\circ C$

1. Pulse width limited by safe operating area

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thJ-PBC}$	Thermal resistance junction-PBC Max	100 <sup>(1)</sup>	$^\circ C/W$
$R_{thJ-PBC}$	Thermal resistance junction-PBC Max	83.5 <sup>(2)</sup>	$^\circ C/W$

1. When Mounted on FR-4 board with 1 inch<sup>2</sup> pad, 2 oz. of Cu. and  $t = 10$  sec.

2. When Mounted on minimum recommended footprint

## 2 Electrical characteristics

( $T_{CASE}=25^{\circ}\text{C}$  unless otherwise specified)

**Table 3. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 250\mu\text{A}$ , $V_{GS} = 0$	20			V
$I_{DSS}$	Zero gate voltage drain current ( $V_{GS} = 0$ )	$V_{DS} = \text{Max rating}$ , $V_{DS} = \text{Max rating @ } 125^{\circ}\text{C}$			1 10	$\mu\text{A}$ $\mu\text{A}$
$I_{GSS}$	Gate body leakage current ( $V_{DS} = 0$ )	$V_{GS} = \pm 12\text{V}$			$\pm 100$	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250\mu\text{A}$	0.6			V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 4.5\text{V}$ , $I_D = 2.5\text{A}$ $V_{GS} = 2.7\text{V}$ , $I_D = 2.5\text{A}$		0.030 0.037	0.040 0.045	$\Omega$ $\Omega$

**Table 4. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$g_{fs}^{(1)}$	Forward transconductance	$V_{DS} = 15\text{V}$ , $I_D = 2.5\text{A}$		9.5		S
$C_{iss}$ $C_{oss}$ $C_{rss}$	Input capacitance Output capacitance Reverse transfer capacitance	$V_{DS} = 15\text{V}$ , $f = 1\text{MHz}$ , $V_{GS} = 0$		460 200 50		pF pF pF
$Q_g$ $Q_{gs}$ $Q_{gd}$	Total gate charge Gate-source charge Gate-drain charge	$V_{DD} = 10\text{V}$ , $I_D = 4.5\text{A}$ $V_{GS} = 4.5\text{V}$		8.5 1.8 2.4	11.5	nC nC nC

1. Pulsed: pulse duration=300 $\mu\text{s}$ , duty cycle 1.5%

**Table 5. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$	Turn-on delay time Rise time Turn-off delay time Fall time	$V_{DD} = 10\text{V}$ , $I_D = 2.5\text{A}$ , $R_G = 4.7\Omega$ , $V_{GS} = 4.5\text{V}$ <i>Figure 13 on page 8</i>		7 33 27 10		ns ns ns ns
$t_{d(off)}$ $t_f$ $t_c$	Off-voltage rise time Fall time Cross-over time	$V_{clamp} = 16\text{V}$ , $I_D = 5\text{A}$ $R_G = 4.7\Omega$ , $V_{GS} = 4.5\text{V}$ <i>Figure 15 on page 8</i>		26 11 21		ns ns ns

**Table 6. Source drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max	Unit
$I_{SD}$	Source-drain current				5	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)				20	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 5A, V_{GS} = 0$			1.2	V
$t_{rr}$ $Q_{rr}$ $I_{RRM}$	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 5A,$ $di/dt = 100A/\mu s,$ $V_{DD} = 10V, T_J = 150^\circ C$ <i>Figure 15 on page 8</i>		26 13 1		ns $\mu C$ A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration=300 $\mu s$ , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

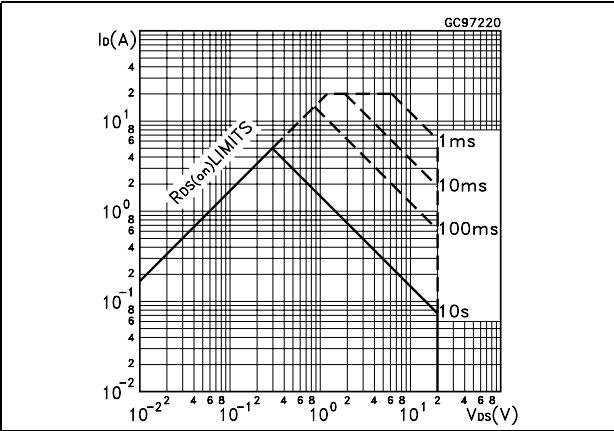


Figure 2. Thermal impedance

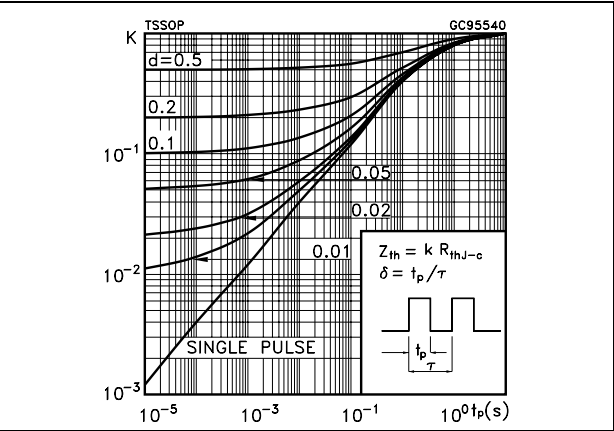


Figure 3. Output characteristics

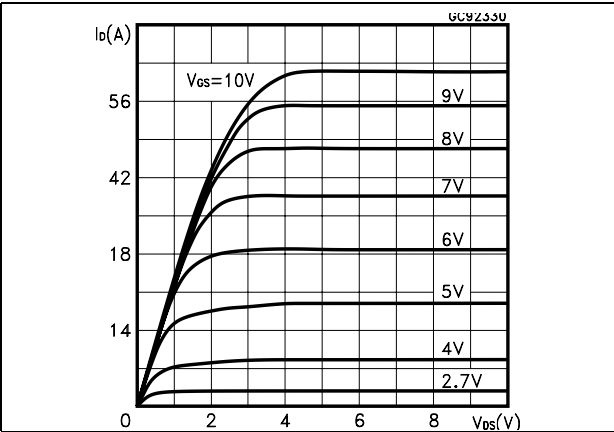


Figure 4. Transfer characteristics

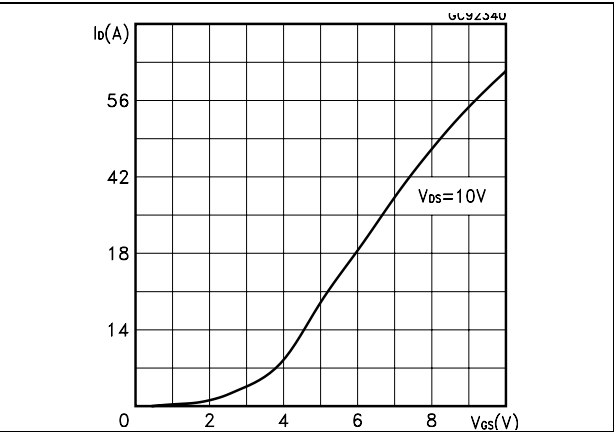


Figure 5. Transconductance

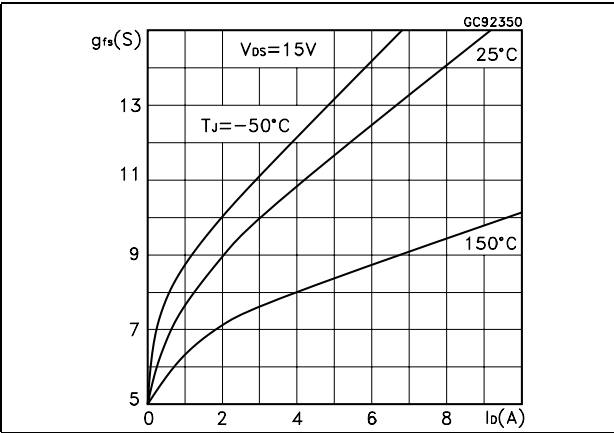


Figure 6. Static drain-source on resistance

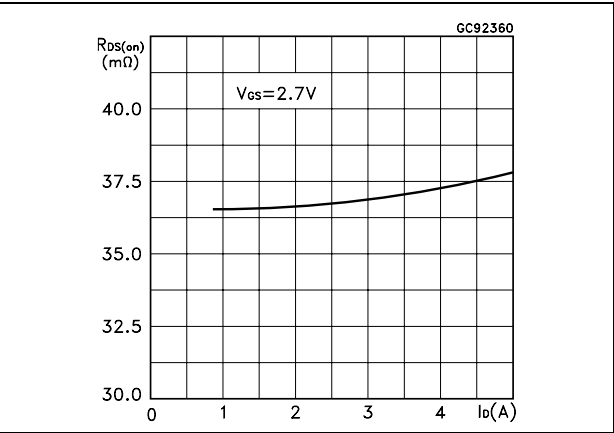


Figure 7. Gate charge vs. gate-source voltage    Figure 8. Capacitance variations

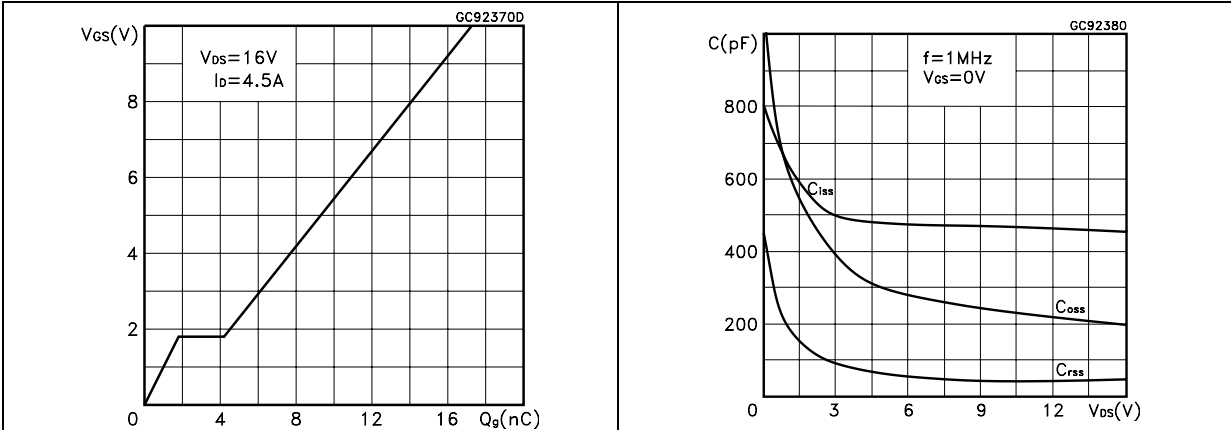


Figure 9. Normalized gate threshold voltage vs. temperature    Figure 10. Normalized on resistance vs. temperature

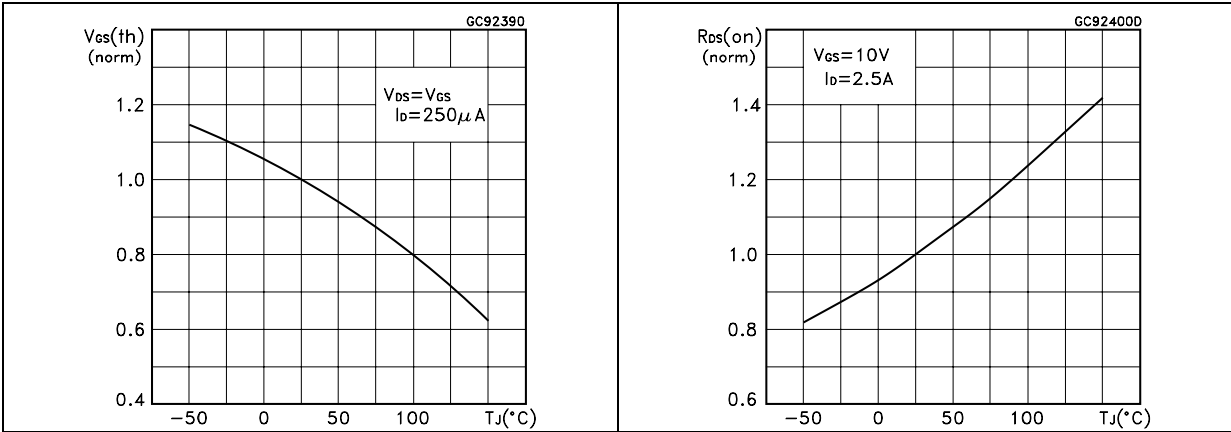
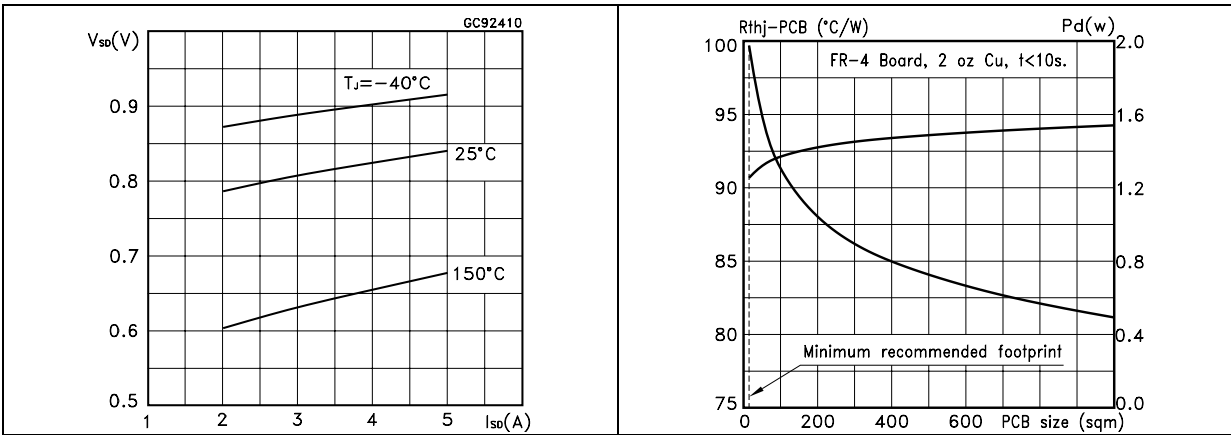
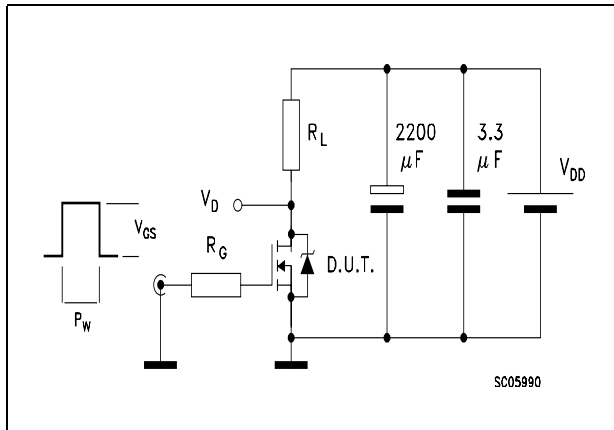


Figure 11. Source-drain diode forward characteristics    Figure 12. Thermal resistance and max power

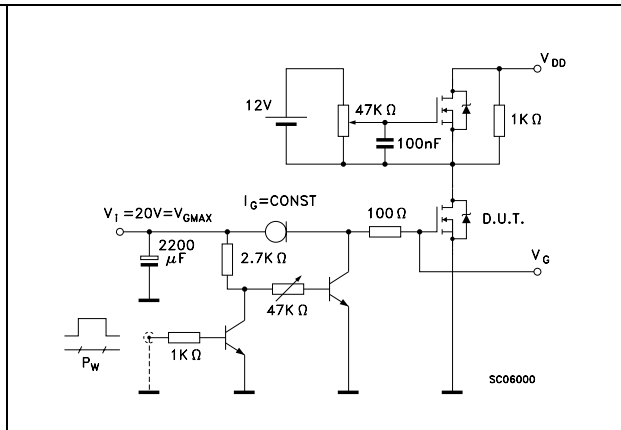


### 3 Test circuit

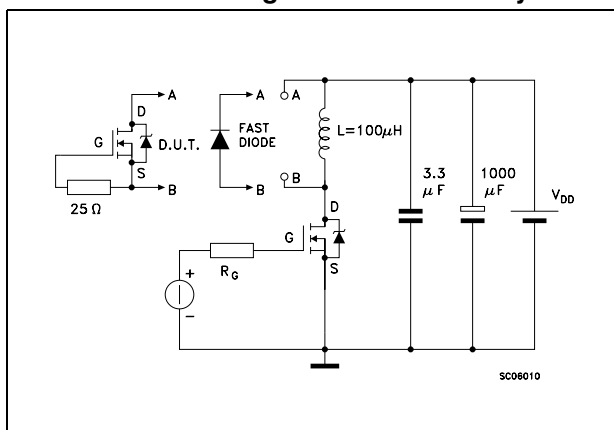
**Figure 13. Switching times test circuit for resistive load**



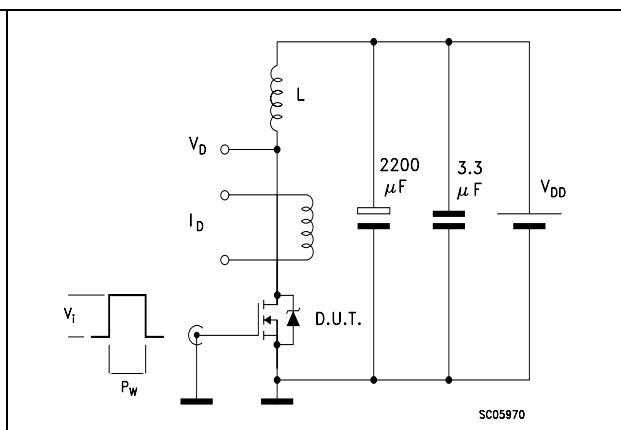
**Figure 14. Gate charge test circuit**



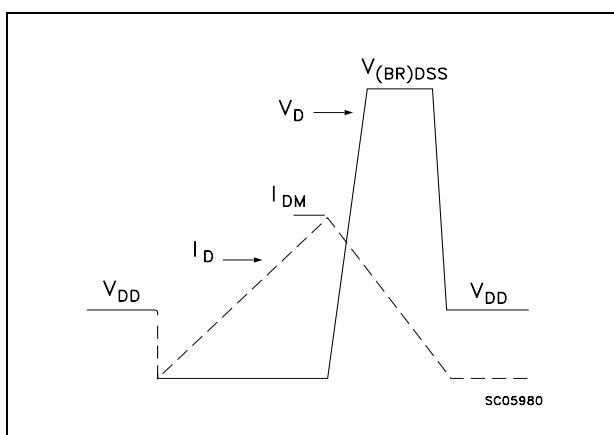
**Figure 15. Test circuit for inductive load switching and diode recovery times**



**Figure 16. Unclamped Inductive load test circuit**



**Figure 17. Unclamped inductive waveform**



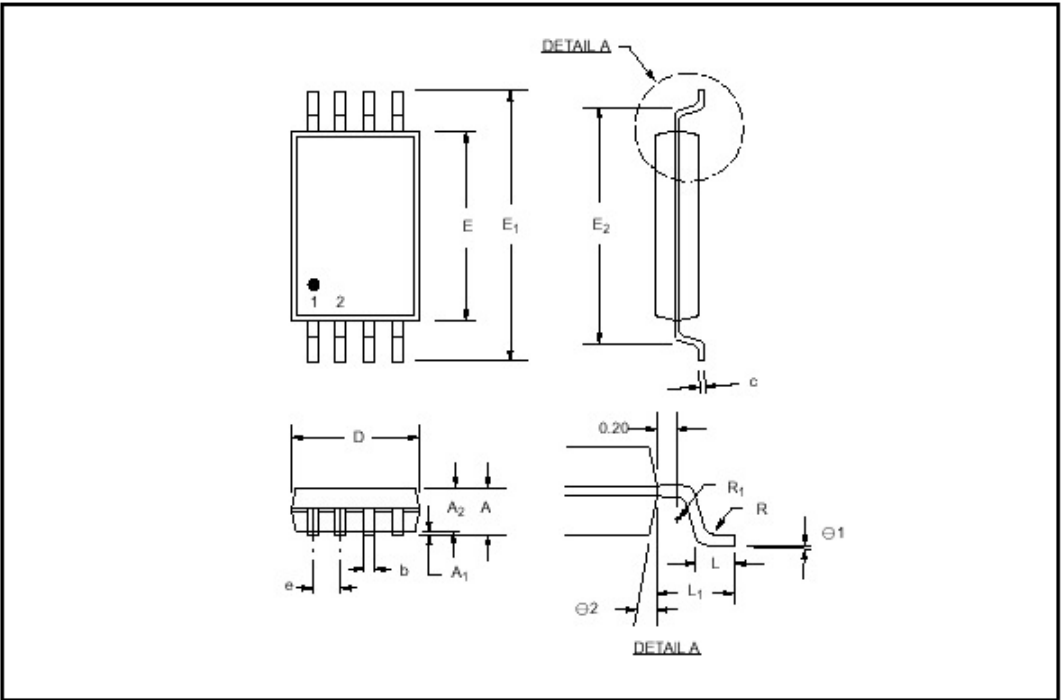


## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com)

TSSOP8 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	1.05		1.20	0.041		0.047
A1	0.05		0.15	0.002		0.006
A2	0.80		1.05	0.032		0.041
b	0.19		0.30	0.008		0.012
c		0.127			0.005	
D	2.90		3.10	0.114		0.122
E	4.30		4.50	0.170		0.177
E1	6.20		6.60	0.240		0.260
E2	5.14		5.24	0.202		0.206
e		0.65			0.025	
L	0.45		0.75	0.018		0.030
L1	0.90		1.10	0.0355		0.0433
R	0.09			0.004		
R1	0.09			0.004		
θ1	0°		8°	0°		8°
θ2	12°					



## 5 Revision history

**Table 7. Revision history**

Date	Revision	Changes
09-Sep-2004	3	Complete version
03-Aug-2006	4	The document has been reformatted, SOA updated
01-Feb-2007	5	Typo mistake on <a href="#">Table 1</a> .

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